

AMENDMENTS TO THE CLAIMS:

Please amend claims 1 and 8 as follows. Please cancel claims 15 and 18. This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently Amended) A resin encapsulating apparatus for forming a resin sealing body on a semiconductor chip mounted on a carrier comprising:
 - a retaining section which retains the carrier on which the semiconductor chip is mounted;
 - a mask set on the carrier and having an opening at which a part of the semiconductor chip is exposed;
 - an extruding section configured to extrude a fluidizing resin in an extruding direction into the opening of the mask;
 - a first drive section which drives the extruding section;
 - a squeegee which causes a movement of the fluidizing resin present over the opening which is extruded from the extruding section into the opening, an interval between the extruding section and the squeegee being set to be wider than a length of the opening in the extruding direction; and
 - a second drive section which drives the squeegee independently of the first drive section which drives the extruding section.

2. (Original) A resin encapsulating apparatus according to claim 1, wherein the first drive section drives the extruding section to be moved over the opening and, during the movement of the extruding section, the extruding section dropwise supplies the fluidizing resin into the opening.

3. (Original) A resin encapsulating apparatus according to claim 1, wherein the first drive section drives the extruding section from one edge end to an opposite edge end of the opening and, during the movement of the extruding section, the extruding section dropwise supplies the fluidizing resin into the opening.

4. (Original) A resin encapsulating apparatus according to claim 3, wherein, when the first drive section moves the extruding section from one edge end to an opposite edge end of the opening, the second drive section drives the squeegee to be moved from behind the extruding section and from one edge end to the opposite edge end of the opening and, during the movement of the squeegee, the squeegee moves the fluidizing resin which is supplied dropwise from the extruding section.

5. (Canceled)

6. (Canceled)

7. (Canceled)

8. (Currently Amended) A resin encapsulating apparatus for forming a protective resin sealing body on a semiconductor chip mounted on a carrier in which the resin sealing body and external connection balls are formed on the same surface side of the semiconductor chip, the resin encapsulating apparatus comprising:

a retaining section which retains the carrier on which the semiconductor chip is mounted;

a mask set on the carrier and having an opening at which, when the mask is set on the carrier, an area of the semiconductor chip at which the resin sealing body is to be formed is exposed;

an extruding section configured to extrude a fluidizing resin in an extruding direction into the opening of the mask;

a first drive section which drives the extruding section;

a squeegee which causes a movement of the fluidizing resin present over the opening which is extruded from the extruding section into the opening, an interval between the extruding section and the squeegee being set to be wider than a length of the opening in the extruding direction; and

a second drive section which drives the squeegee independently of the first drive section which drives the extruding section.

9. (Original) A resin encapsulating apparatus according to claim 8, wherein the first drive section drives the extruding section to be moved over the opening and, during the movement of the extruding section, the extruding section dropwise supplies the fluidizing resin into the opening.

10. (Original) A resin encapsulating apparatus according to claim 8, wherein the first drive section drives the extruding section and moves the extruding section from one edge end to an opposite edge end of the opening and, during the movement of the extruding section, the extruding section dropwise supplies the fluidizing resin into the opening.

11. (Original) A resin encapsulating apparatus according to claim 9, wherein, when the first drive section moves the extruding section from one edge end to the opposite edge end of the opening, the second drive section drives the squeegee to be moved from behind the extruding section and from one edge end to the opposite edge end of the opening and, during the movement of the squeegee, the squeegee moves the fluidizing resin which is supplied dropwise from the extruding section.

12. - 21. (Canceled)

22. (Previously Presented) A resin encapsulating apparatus according to claim 1, wherein the squeegee moves separately from the extruding section.

23. (Previously Presented) A resin encapsulating apparatus according to claim 1, wherein the second drive section causes the squeegee to come into contact with one side of the opening of the mask, to move to another side of the opening which is opposed to the one side of the opening, and then to move away from the mask.

24. (Canceled)

25. (Previously Presented) A resin encapsulating apparatus according to claim 8, wherein the squeegee moves separately from the extruding section.

26. (Previously Presented) A resin encapsulating apparatus according to claim 8, wherein the second drive section causes the squeegee to come into contact with one side of the opening of the mask, to move another side of the opening which is opposed to the one side of the opening, and to move away from the mask.

27. (New) A resin encapsulating apparatus for forming a resin sealing body on a semiconductor chip mounted on a carrier comprising:

a retaining section which retains the carrier on which the semiconductor chip is mounted;

a mask set on the carrier and having an opening at which a part of the semiconductor chip is exposed;

an extruding section configured to extrude a fluidizing resin in an extruding direction into the opening of the mask;

a first drive section which drives the extruding section;

a squeegee which causes a movement of the fluidizing resin present over the opening which is extruded from the extruding section into the opening, an interval between the extruding section and the squeegee being set to be shorter than a length of the opening in the extruding direction; and

a second drive section which drives the squeegee independently of the first drive section which drives the extruding section.

28. (New) A resin encapsulating apparatus for forming a protective resin sealing body on a semiconductor chip mounted on a carrier in which the resin sealing body and external

connection balls are formed on the same surface side of the semiconductor chip, the resin encapsulating apparatus comprising:

- a retaining section which retains the carrier on which the semiconductor chip is mounted;

- a mask set on the carrier and having an opening at which, when the mask is set on the carrier, an area of the semiconductor chip at which the resin sealing body is to be formed is exposed;

- an extruding section configured to extrude a fluidizing resin in an extruding direction into the opening of the mask;

- a first drive section which drives the extruding section;

- a squeegee which causes a movement of the fluidizing resin present over the opening which is extruded from the extruding section into the opening, an interval between the extruding section and the squeegee being set to be shorter than a length of the opening in the extruding direction; and

- a second drive section which drives the squeegee independently of the first drive section which drives the extruding section.

AMENDMENTS TO THE DRAWINGS:

The attached sheets of drawings includes changes to Figs. 3A-3D, 5A-5D, and 6A-6D. Details of the changes are discussed in the remarks following the amendment sections of this paper.

Attachments: Replacement Sheets containing Figs. 3A-3D, 5A-5D, and 6A-6D